

Features:

- Isolated mounting base 3000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

V _{RSM}	V _{RRM}	Type & Outline
900V	800V	MDx300-08-413F3D
1100V	1000V	MDx300-10-413F3D
1300V	1200V	MDx300-12-413F3D
1500V	1400V	MDx300-14-413F3D
1700V	1600V	MDx300-16-413F3D
1900V	1800V	MDx300-18-413F3D

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _J (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			300	A
I _{F(RMS)}	RMS forward current		150			471	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			20	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			10	KA
I ² t	I ² T for fusing coordination	V _R =0.6V _{RRM}				500	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.75	V
r _F	Forward slop resistance					0.55	mΩ
V _{FM}	Peak forward voltage	I _{FM} =900A	25			1.35	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.130	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.04	°C /W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(max)		3000			V
F _m	Terminal connection torque(M8)				12.0		N·m
	Mounting torque(M6)				6.0		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				820		g
Outline	413F3D						

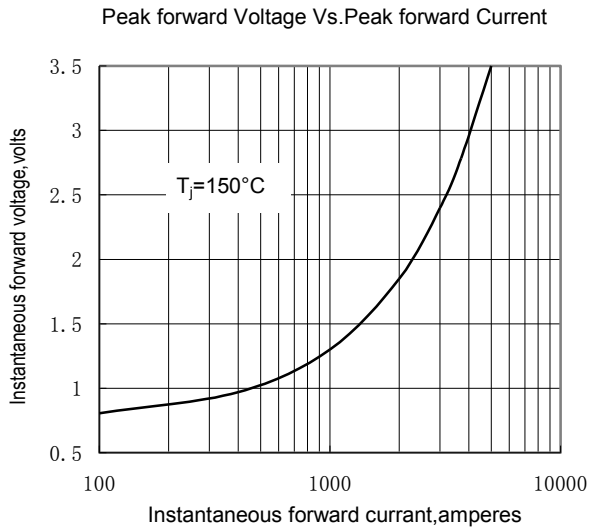


Fig.1

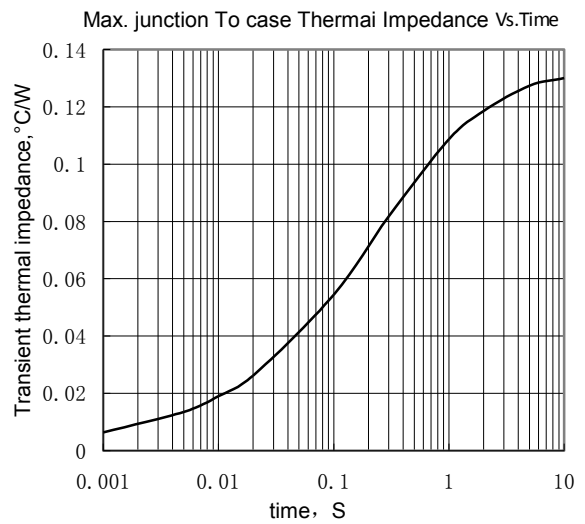


Fig.2

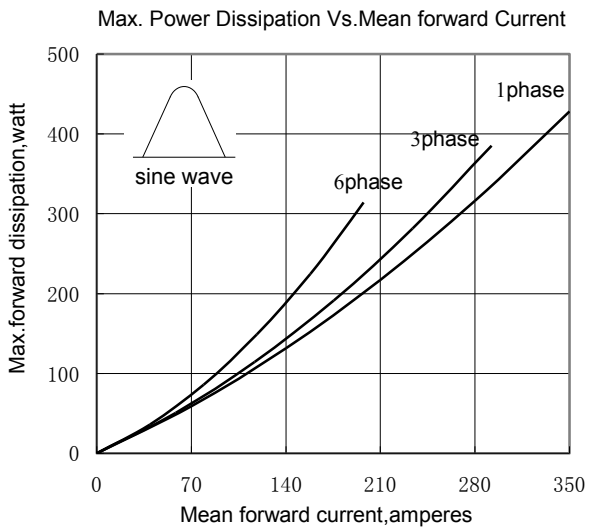


Fig.3

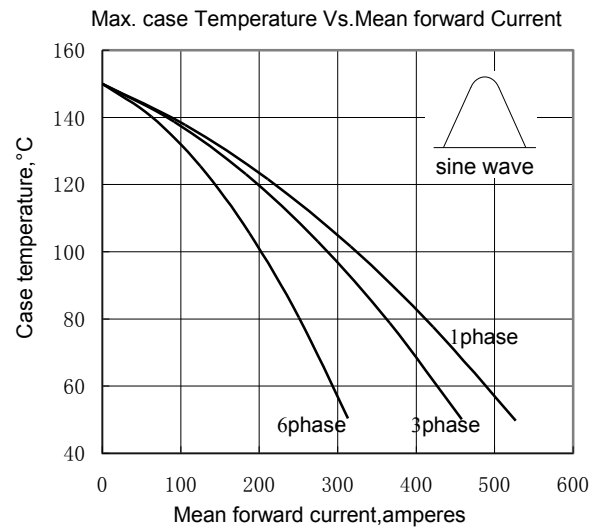


Fig.4

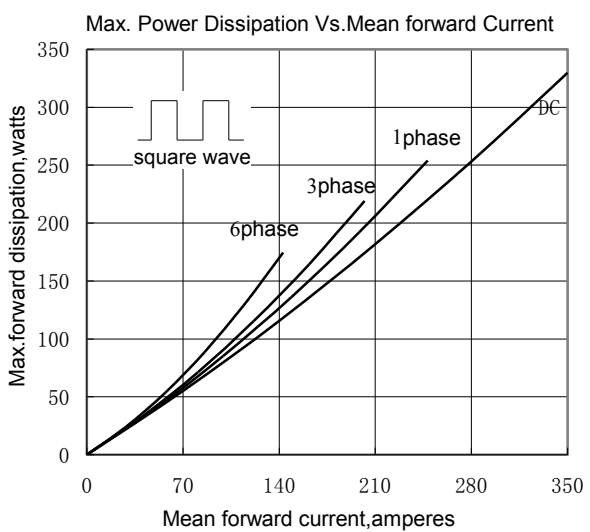


Fig.5

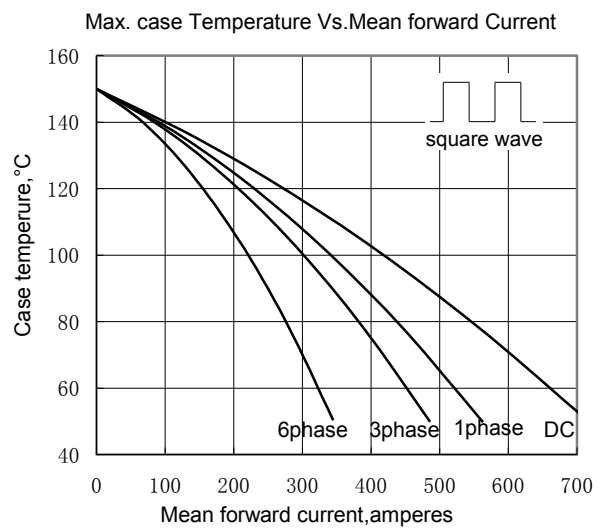


Fig.6

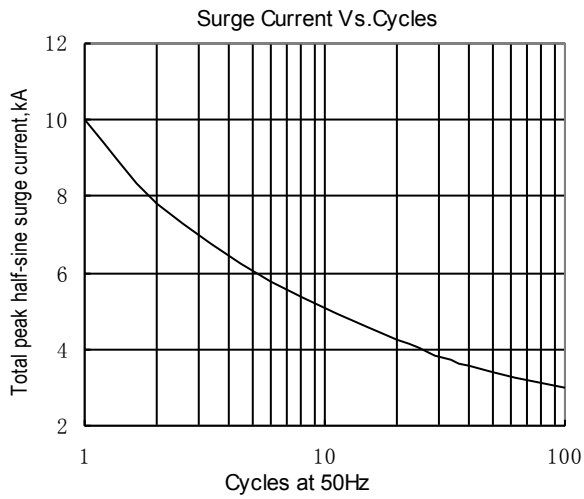


Fig.7

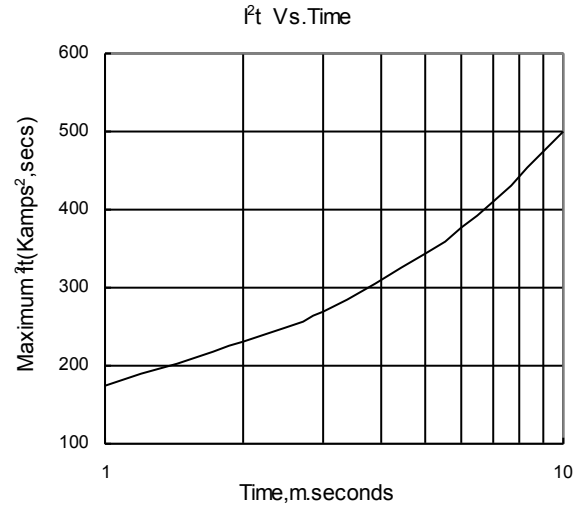
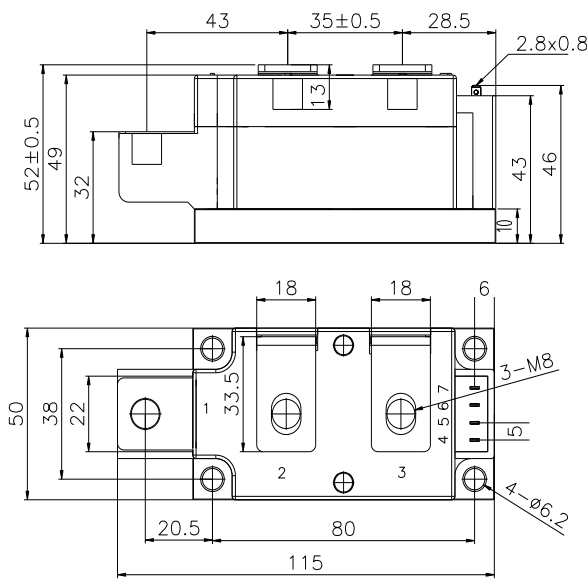


Fig.8

Outline:



413F3D

